

WHAT IS CLAIMED IS:

1. A jig structure for an integrated circuit package, the jig structure being used for integrated circuits to be covered by glue, the jig structure comprising:

5 a base formed with a plurality of receiving regions for receiving the integrated circuits;

a mold plate covering the base;

a plurality of glue inlets formed on the mold plate at locations corresponding to each receiving region on the base; and

10 a projection arranged between each glue inlet and its corresponding receiving region, wherein the projection blocks and buffers the glue entering the receiving regions from the glue inlets.

2. The jig structure for an integrated circuit package according to claim 1, wherein the projection on the mold plate is a strip-shaped projection.

15 3. The jig structure for an integrated circuit package according to claim 1, wherein the glue enters the receiving regions through apertures formed between the projection on the mold plate and the base.